

**EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("6297140").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/20 18:14
S2	2	("5244833").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/20 18:58
S3	6	("1770597").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/20 19:21
S4	2	("5316974").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/20 21:06
S5	90	("4272561"   "4352716"   "4742014"   "4767724").PN. OR ("5316974").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/20 21:11
S6	2	("5010389").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/21 16:00
S8	18632766	@ad<"19980109"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:30
S11	8	S8 and S10	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/21 17:34
S10	90	("4272561"   "4352716"   "4742014"   "4767724").PN. OR ("5316974").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/21 17:34
S23	96940	CMP (chemical near mechanical near polish\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:45
S22	19609	seed same (copper Cu)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:45

S21	5027	(alpha ".alpha.") with (TaN (tantalum near nitride) tantalum)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:45
S20	281151	sputter\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:45
S19	100546	electro\$1plat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:45
S18	96940	CMP (chemical near mechanical near polish\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:45
S24	81016	solder same (lead tin lead \$1free)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:46
S25	2082788	oxide (silicon near (oxide dioxide)) "SiO.sub.2"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:56
S29	10	S19 and S25 and S26 and S27 and S22 and S21 and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:58
S28	21	S19 and S25 and S26 and S27 and S22 and S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:58
S27	512613	polyimide polyamide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:58
S26	409263	nitride (silicon near nitride) "Si.sub.2N.sub.4"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:58
S32	3	08/497065	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:59

S31	1	S29 and S8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:59
S30	1	S28 and S8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/21 17:59
S33	2	("6140234").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/24 10:45
S34	151	(alpha ".alpha.") with (TaN (tantalum near nitride) tantalum) same barrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 10:49
S35	2210	(electrolytic electroless) with seed with (Cu copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 12:16
S37	148	S35 and S36	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 12:36
S36	18632871	@ad<"19980109"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 12:36
S39	348	S36 and S38	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:32
S38	1736	photo\$1resist with (spin-on spun-on spin\$1on spun \$1on)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:32
S41	36	S39 and S40	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:33
S40	100599	electro\$1plat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:33

S42	123839	(method with appl\$7 with photo\$1resist) same spin spun	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:41
S43	60340	S42 and S36	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:45
S44	579	S43 and S40	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:46
S46	367	S45 and S36	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:47
S45	1156	(method with appl\$7 with photo\$1resist) same (spin spun)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 14:47
S47	6	("5316974") or ("5891802") or ("5834827").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/24 15:13
S48	2	"5244833").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/24 15:21
S49	97012	CMP (chemical near mechanical near polish\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 16:01
S52	2924446	trench groove recess	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 16:03
S51	33	S50 and S36	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 16:03
S50	1246	S49 and S40 and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 16:03

S53	15	S51 and S52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/24 16:04
S54	2	("5736456").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/24 16:37

3/26/2008 11:40:06 AM

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